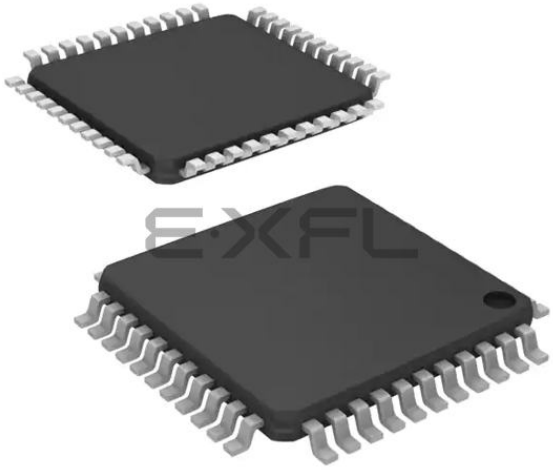

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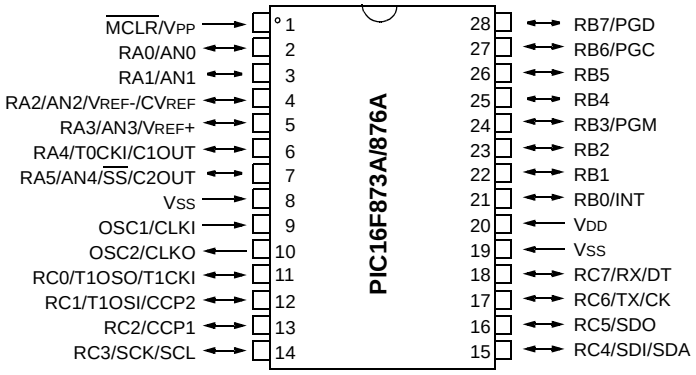
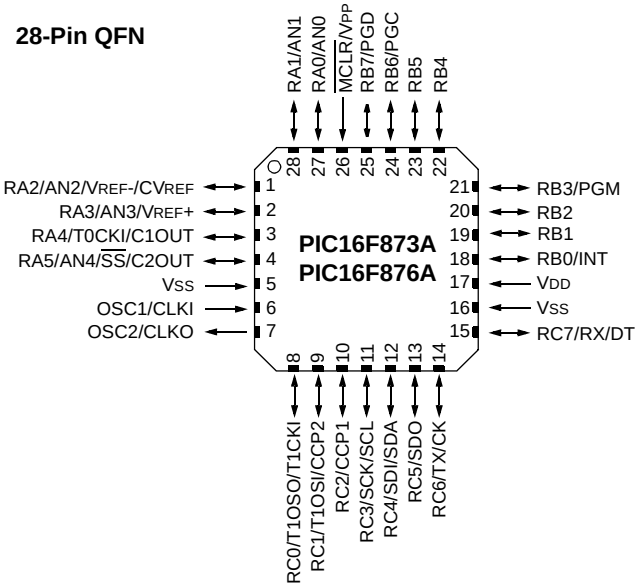
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f877at-i-pt

Pin Diagrams

28-Pin PDIP, SOIC, SSOP



28-Pin QFN



44-Pin QFN

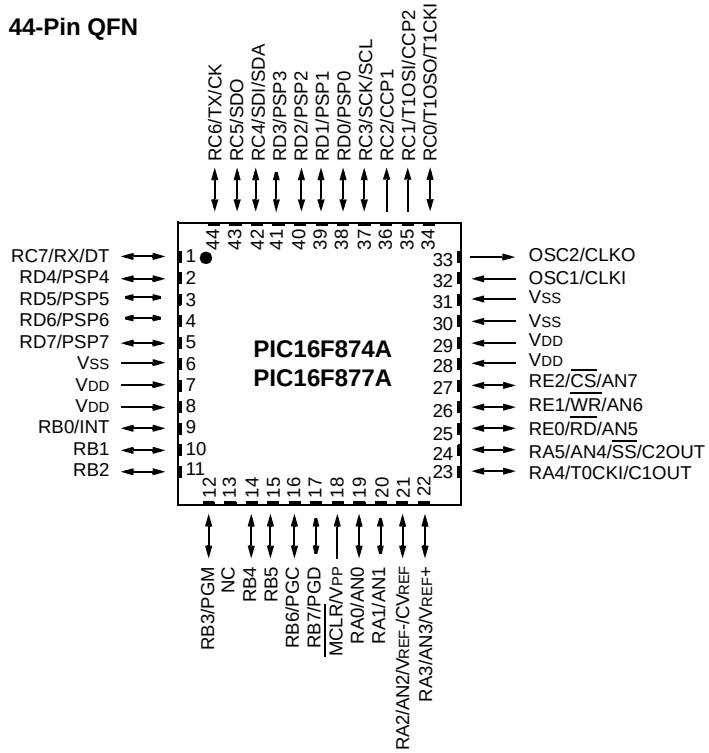


TABLE 1-2: PIC16F873A/876A PINOUT DESCRIPTION (CONTINUED)

Pin Name	PDIP, SOIC, SSOP Pin#	QFN Pin#	I/O/P Type	Buffer Type	Description
					PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT	21	18		TTL/ST(1)	
RB0			I/O		Digital I/O.
INT			I		External interrupt.
RB1	22	19	I/O	TTL	Digital I/O.
RB2	23	20	I/O	TTL	Digital I/O.
RB3/PGM	24	21		TTL	
RB3			I/O		Digital I/O.
PGM			I		Low-voltage (single-supply) ICSP programming enable pin.
RB4	25	22	I/O	TTL	Digital I/O.
RB5	26	23	I/O	TTL	Digital I/O.
RB6/PGC	27	24		TTL/ST(2)	
RB6			I/O		Digital I/O.
PGC			I		In-circuit debugger and ICSP programming clock.
RB7/PGD	28	25		TTL/ST(2)	
RB7			I/O		Digital I/O.
PGD			I/O		In-circuit debugger and ICSP programming data.
					PORTC is a bidirectional I/O port.
RC0/T1OSO/T1CKI	11	8		ST	
RC0			I/O		Digital I/O.
T1OSO			O		Timer1 oscillator output.
T1CKI			I		Timer1 external clock input.
RC1/T1OSI/CCP2	12	9		ST	
RC1			I/O		Digital I/O.
T1OSI			I		Timer1 oscillator input.
CCP2			I/O		Capture2 input, Compare2 output, PWM2 output.
RC2/CCP1	13	10		ST	
RC2			I/O		Digital I/O.
CCP1			I/O		Capture1 input, Compare1 output, PWM1 output.
RC3/SCK/SCL	14	11		ST	
RC3			I/O		Digital I/O.
SCK			I/O		Synchronous serial clock input/output for SPI mode.
SCL			I/O		Synchronous serial clock input/output for I^2C mode.
RC4/SDI/SDA	15	12		ST	
RC4			I/O		Digital I/O.
SDI			I		SPI data in.
SDA			I/O		I^2C data I/O.
RC5/SDO	16	13		ST	
RC5			I/O		Digital I/O.
SDO			O		SPI data out.
RC6/TX/CK	17	14		ST	
RC6			I/O		Digital I/O.
TX			O		USART asynchronous transmit.
CK			I/O		USART1 synchronous clock.
RC7/RX/DT	18	15		ST	
RC7			I/O		Digital I/O.
RX			I		USART asynchronous receive.
DT			I/O		USART synchronous data.
VSS	8, 19	5, 6	P	—	Ground reference for logic and I/O pins.
VDD	20	17	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.

TABLE 1-3: PIC16F874A/877A PINOUT DESCRIPTION

Pin Name	PDIP Pin#	PLCC Pin#	TQFP Pin#	QFN Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKI	13	14	30	32		ST/CMOS(4)	Oscillator crystal or external clock input.
OSC1					I		Oscillator crystal input or external clock source input. ST buffer when configured in RC mode; otherwise CMOS.
CLKI					I		External clock source input. Always associated with pin function OSC1 (see OSC1/CLKI, OSC2/CLKO pins).
OSC2/CLKO	14	15	31	33		—	Oscillator crystal or clock output.
OSC2					O		Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO					O		In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	2	18	18		ST	Master Clear (input) or programming voltage (output).
$\overline{MCLR}$					I		Master Clear (Reset) input. This pin is an active low Reset to the device.
VPP					P		Programming voltage input.
							PORTA is a bidirectional I/O port.
RA0/AN0	2	3	19	19		TTL	
RA0					I/O		Digital I/O.
AN0					I		Analog input 0.
RA1/AN1	3	4	20	20		TTL	
RA1					I/O		Digital I/O.
AN1					I		Analog input 1.
RA2/AN2/VREF-/CVREF	4	5	21	21		TTL	
RA2					I/O		Digital I/O.
AN2					I		Analog input 2.
VREF-					I		A/D reference voltage (Low) input.
CVREF					O		Comparator VREF output.
RA3/AN3/VREF+	5	6	22	22		TTL	
RA3					I/O		Digital I/O.
AN3					I		Analog input 3.
VREF+					I		A/D reference voltage (High) input.
RA4/T0CKI/C1OUT	6	7	23	23		ST	
RA4					I/O		Digital I/O – Open-drain when configured as output.
T0CKI					I		Timer0 external clock input.
C1OUT					O		Comparator 1 output.
RA5/AN4/$\overline{SS}$/C2OUT	7	8	24	24		TTL	
RA5					I/O		Digital I/O.
AN4					I		Analog input 4.
$\overline{SS}$					I		SPI slave select input.
C2OUT					O		Comparator 2 output.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Details on page:
Bank 1											
80h(3)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	31, 150
81h	OPTION_REG	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	23, 150
82h(3)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	30, 150
83h(3)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	22, 150
84h(3)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	31, 150
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	43, 150
86h	TRISB	PORTB Data Direction Register								1111 1111	45, 150
87h	TRISC	PORTC Data Direction Register								1111 1111	47, 150
88h(4)	TRISD	PORTD Data Direction Register								1111 1111	48, 151
89h(4)	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction bits			0000 -111	50, 151
8Ah(1,3)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	30, 150
8Bh(3)	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	24, 150
8Ch	PIE1	PSPIE(2)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	25, 151
8Dh	PIE2	—	CMIE	—	EEIE	BCLIE	—	—	CCP2IE	-0-0 0--0	27, 151
8Eh	PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$	---- --qq	29, 151
8Fh	—	Unimplemented								—	—
90h	—	Unimplemented								—	—
91h	SSPCON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	83, 151
92h	PR2	Timer2 Period Register								1111 1111	62, 151
93h	SSPADD	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	79, 151
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	79, 151
95h	—	Unimplemented								—	—
96h	—	Unimplemented								—	—
97h	—	Unimplemented								—	—
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	111, 151
99h	SPBRG	Baud Rate Generator Register								0000 0000	113, 151
9Ah	—	Unimplemented								—	—
9Bh	—	Unimplemented								—	—
9Ch	CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	0000 0111	135, 151
9Dh	CVRCON	CVREN	CVROE	CVRR	—	CVR3	CVR2	CVR1	CVR0	000- 0000	141, 151
9Eh	ADRESL	A/D Result Register Low Byte								xxxx xxxx	133, 151
9Fh	ADCON1	ADFM	ADCS2	—	—	PCFG3	PCFG2	PCFG1	PCFG0	00-- 0000	128, 151

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8>, whose contents are transferred to the upper byte of the program counter.

2: Bits PSPIE and PSPIF are reserved on PIC16F873A/876A devices; always maintain these bits clear.

3: These registers can be addressed from any bank.

4: PORTD, PORTE, TRISD and TRISE are not implemented on PIC16F873A/876A devices, read as '0'.

5: Bit 4 of EEADRH implemented only on the PIC16F876A/877A devices.

2.2.2.5 PIR1 Register

The PIR1 register contains the individual flag bits for the peripheral interrupts.

Note:	Interrupt flag bits are set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt bits are clear prior to enabling an interrupt.

REGISTER 2-5: PIR1 REGISTER (ADDRESS 0Ch)

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit 7							bit 0

bit 7 **PSPIF:** Parallel Slave Port Read/Write Interrupt Flag bit(1)
1 = A read or a write operation has taken place (must be cleared in software)
0 = No read or write has occurred

Note 1: PSPIF is reserved on PIC16F873A/876A devices; always maintain this bit clear.

bit 6 **ADIF**: A/D Converter Interrupt Flag bit
1 = An A/D conversion completed
0 = The A/D conversion is not complete

bit 5 **RCIF**: USART Receive Interrupt Flag bit
1 = The USART receive buffer is full
0 = The USART receive buffer is empty

bit 4 **TXIF**: USART Transmit Interrupt Flag bit
1 = The USART transmit buffer is empty
0 = The USART transmit buffer is full

bit 3 **SSPIF**: Synchronous Serial Port (SSP) Interrupt Flag bit
1 = The SSP interrupt condition has occurred and must be cleared in software before returning from the Interrupt Service Routine. The conditions that will set this bit are:
- SPI – A transmission/reception has taken place.
- I^2C Slave – A transmission/reception has taken place.
- I^2C Master
  - A transmission/reception has taken place.
  - The initiated Start condition was completed by the SSP module.
  - The initiated Stop condition was completed by the SSP module.
  - The initiated Restart condition was completed by the SSP module.
  - The initiated Acknowledge condition was completed by the SSP module.
  - A Start condition occurred while the SSP module was Idle (multi-master system).
  - A Stop condition occurred while the SSP module was Idle (multi-master system).

0 = No SSP interrupt condition has occurred

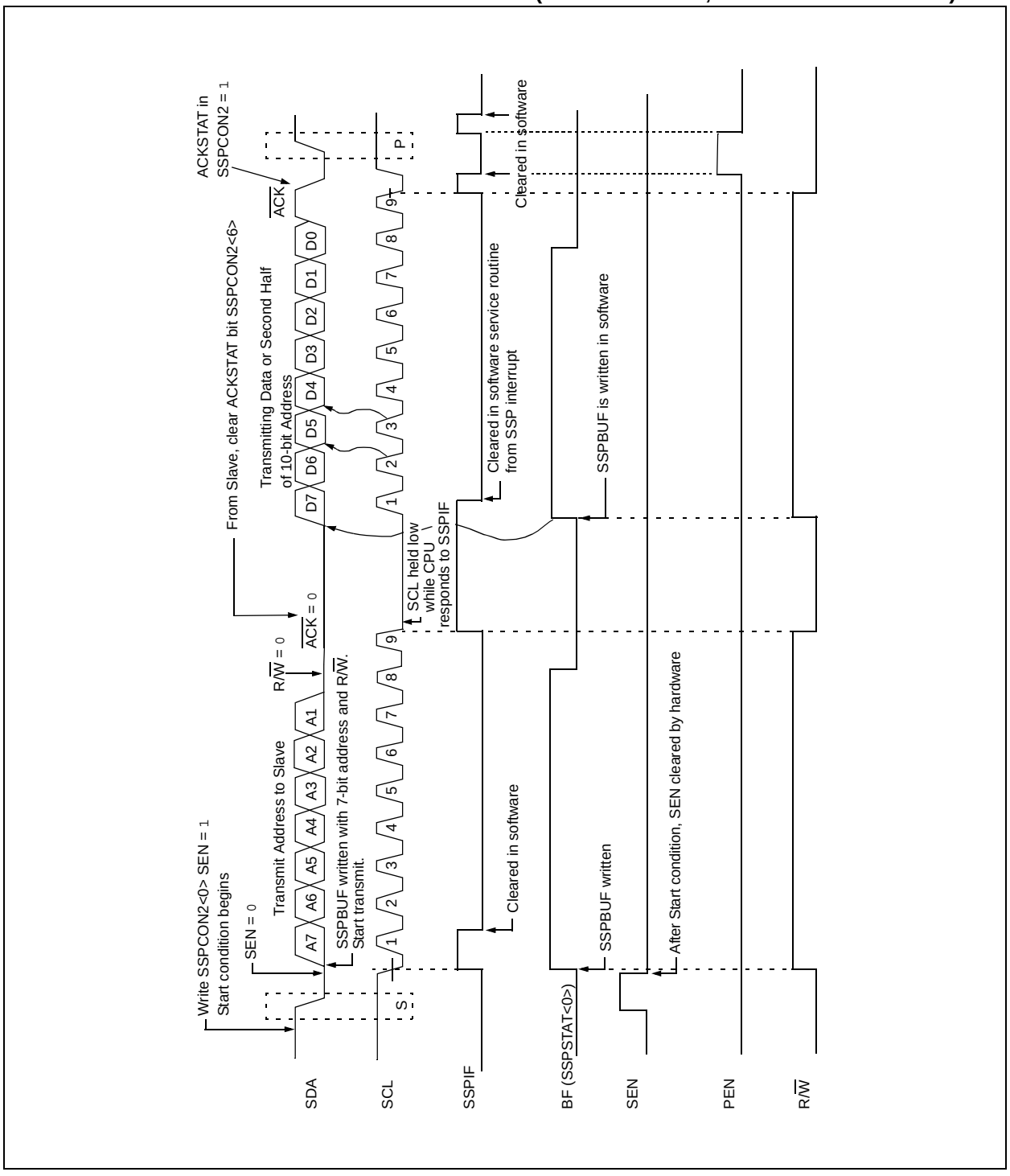
bit 2 **CCP1IF**: CCP1 Interrupt Flag bit
Capture mode:
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare mode:
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM mode:
Unused in this mode.

bit 1 **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0 **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflowed (must be cleared in software)
0 = TMR1 register did not overflow

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

FIGURE 9-21: I²C MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



9.4.14 SLEEP OPERATION

While in Sleep mode, the I^2C module can receive addresses or data and when an address match or complete byte transfer occurs, wake the processor from Sleep (if the MSSP interrupt is enabled).

9.4.15 EFFECT OF A RESET

A Reset disables the MSSP module and terminates the current transfer.

9.4.16 MULTI-MASTER MODE

In Multi-Master mode, the interrupt generation on the detection of the Start and Stop conditions allows the determination of when the bus is free. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSP module is disabled. Control of the I^2C bus may be taken when the P bit (SSPSTAT<4>) is set, or the bus is Idle, with both the S and P bits clear. When the bus is busy, enabling the SSP interrupt will generate the interrupt when the Stop condition occurs.

In multi-master operation, the SDA line must be monitored for arbitration to see if the signal level is at the expected output level. This check is performed in hardware with the result placed in the BCLIF bit.

The states where arbitration can be lost are:

- Address Transfer
- Data Transfer
- A Start Condition
- A Repeated Start Condition
- An Acknowledge Condition

9.4.17 MULTI -MASTER COMMUNICATION, BUS COLLISION AND BUS ARBITRATION

Multi-Master mode support is achieved by bus arbitration. When the master outputs address/data bits onto the SDA pin, arbitration takes place when the master outputs a '1' on SDA by letting SDA float high and another master asserts a '0'. When the SCL pin floats high, data should be stable. If the expected data on SDA is a '1' and the data sampled on the SDA pin = 0, then a bus collision has taken place. The master will set the Bus Collision Interrupt Flag, BCLIF, and reset the I^2C port to its Idle state (Figure 9-25).

If a transmit was in progress when the bus collision occurred, the transmission is halted, the BF flag is cleared, the SDA and SCL lines are deasserted and the SSPBUF can be written to. When the user services the bus collision Interrupt Service Routine and if the I^2C bus is free, the user can resume communication by asserting a Start condition.

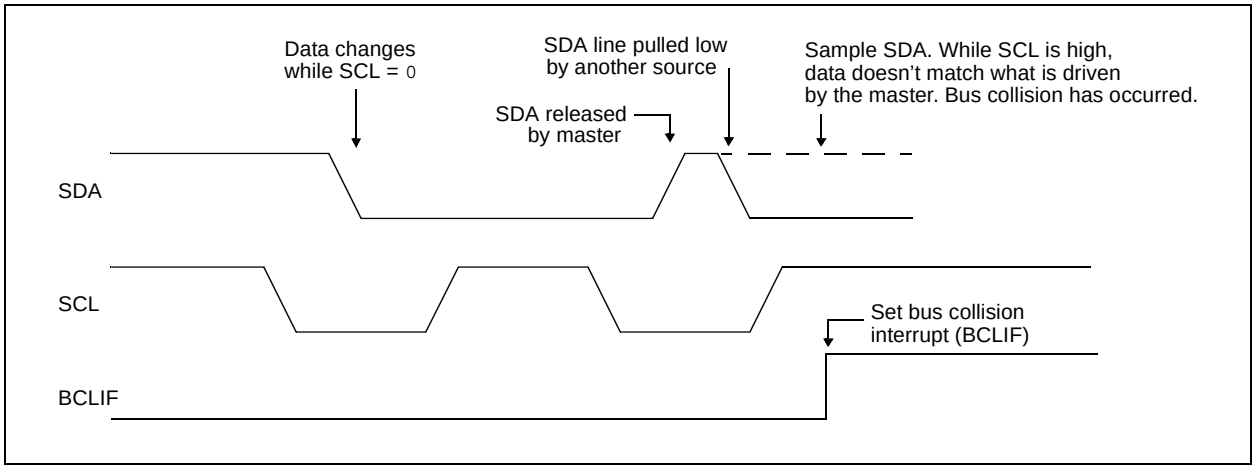
If a Start, Repeated Start, Stop or Acknowledge condition was in progress when the bus collision occurred, the condition is aborted, the SDA and SCL lines are deasserted and the respective control bits in the SSPCON2 register are cleared. When the user services the bus collision Interrupt Service Routine and if the I^2C bus is free, the user can resume communication by asserting a Start condition.

The Master will continue to monitor the SDA and SCL pins. If a Stop condition occurs, the SSPIF bit will be set.

A write to the SSPBUF will start the transmission of data at the first data bit regardless of where the transmitter left off when the bus collision occurred.

In Multi-Master mode, the interrupt generation on the detection of Start and Stop conditions allows the determination of when the bus is free. Control of the I^2C bus can be taken when the P bit is set in the SSPSTAT register or the bus is Idle and the S and P bits are cleared.

FIGURE 9-25: BUS COLLISION TIMING FOR TRANSMIT AND ACKNOWLEDGE



10.2 USART Asynchronous Mode

In this mode, the USART uses standard Non-Return-to-Zero (NRZ) format (one Start bit, eight or nine data bits and one Stop bit). The most common data format is 8 bits. An on-chip, dedicated, 8-bit Baud Rate Generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The transmitter and receiver are functionally independent but use the same data format and baud rate. The baud rate generator produces a clock, either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during Sleep.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

10.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 10-1. The heart of the transmitter is the Transmit (Serial) Shift Register (TSR). The shift register obtains its data from the Read/Write Transmit Buffer, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the Stop bit has been transmitted from the previous load. As soon as the Stop bit is transmitted, the TSR is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one TCY), the TXREG register is empty and flag bit, TXIF (PIR1<4>), is set. This interrupt can be enabled/disabled by setting/clearing enable bit, TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>), shows the status of the TSR register. Status bit TRMT is a read-only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit so the user has to poll this bit in order to determine if the TSR register is empty.

Note 1:	The TSR register is not mapped in data memory so it is not available to the user.
2:	Flag bit TXIF is set when enable bit TXEN is set. TXIF is cleared by loading TXREG.

Transmission is enabled by setting enable bit, TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the Baud Rate Generator (BRG) has produced a shift clock (Figure 10-2). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally, when transmission is first started, the TSR register is empty. At that point, transfer to the TXREG register will result in an immediate transfer to TSR, resulting in an empty TXREG. A back-to-back transfer is thus possible (Figure 10-3). Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. As a result, the RC6/TX/CK pin will revert to high-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit may be loaded in the TSR register.

FIGURE 10-1: USART TRANSMIT BLOCK DIAGRAM

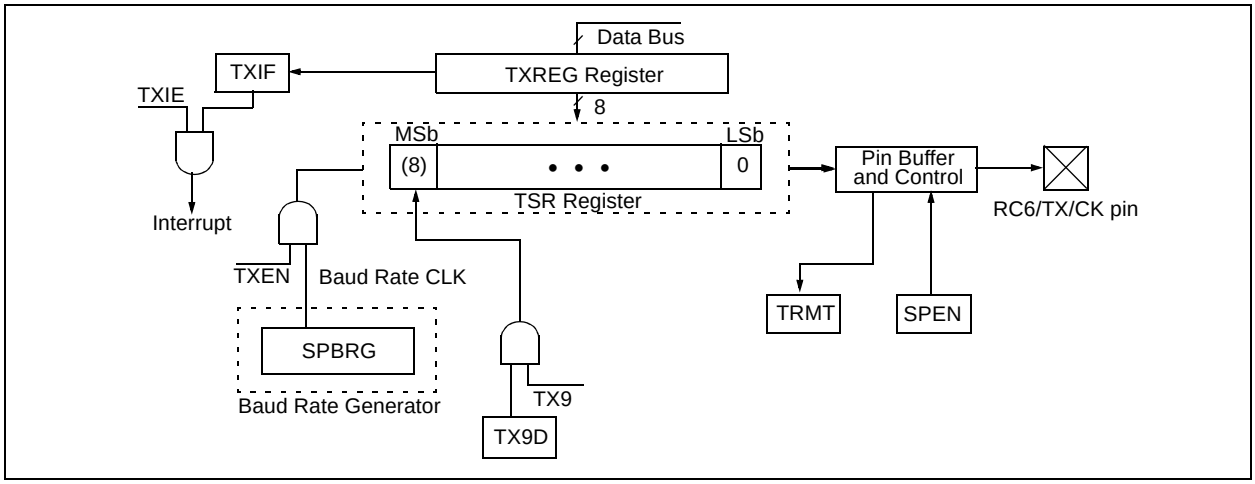


TABLE 12-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on all other Resets
9Ch	CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	0000 0111	0000 0111
9Dh	CVRCON	CVREN	CVROE	CVRR	—	CVR3	CVR2	CVR1	CVR0	000- 0000	000- 0000
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE/ GIEH	PEIE/ GIEL	TMR0IE	INTIE	RBIE	TMR0IF	INTIF	RBIF	0000 000x	0000 000u
0Dh	PIR2	—	CMIF	—	—	BCLIF	LVDIF	TMR3IF	CCP2IF	-0-- 0000	-0-- 0000
8Dh	PIE2	—	CMIE	—	—	BCLIE	LVDIE	TMR3IE	CCP2IE	-0-- 0000	-0-- 0000
05h	PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--0x 0000	--0u 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are unused by the comparator module.

14.0 SPECIAL FEATURES OF THE CPU

All PIC16F87XA devices have a host of features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator Selection
- Reset
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Sleep
- Code Protection
- ID Locations
- In-Circuit Serial Programming
- Low-Voltage In-Circuit Serial Programming
- In-Circuit Debugger

PIC16F87XA devices have a Watchdog Timer which can be shut-off only through configuration bits. It runs off its own RC oscillator for added reliability.

There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only. It is designed to keep the part in Reset while the power supply stabilizes. With these two timers on-chip, most applications need no external Reset circuitry.

Sleep mode is designed to offer a very low current power-down mode. The user can wake-up from Sleep through external Reset, Watchdog Timer wake-up or through an interrupt.

Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits is used to select various options.

Additional information on special features is available in the PIC® Mid-Range MCU Family Reference Manual (DS33023).

14.1 Configuration Bits

The configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1') to select various device configurations. The erased or unprogrammed value of the Configuration Word register is 3FFFh. These bits are mapped in program memory location 2007h.

It is important to note that address 2007h is beyond the user program memory space which can be accessed only during programming.

14.2 Oscillator Configurations

14.2.1 OSCILLATOR TYPES

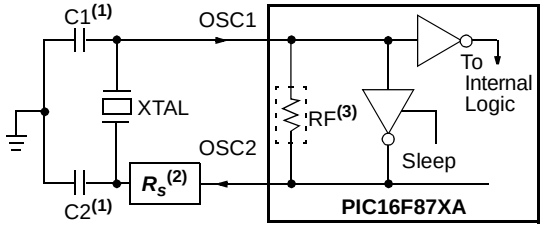
The PIC16F87XA can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High-Speed Crystal/Resonator
- RC Resistor/Capacitor

14.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKI and OSC2/CLKO pins to establish oscillation (Figure 14-1). The PIC16F87XA oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKI pin (Figure 14-2).

FIGURE 14-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 14-1 and Table 14-2 for recommended values of C1 and C2.

2: A series resistor (R_S) may be required for AT strip cut crystals.

3: RF varies with the crystal chosen.

FIGURE 14-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

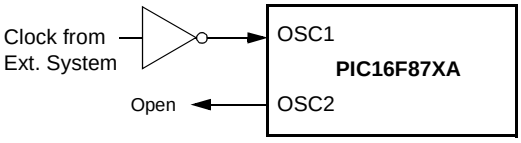


TABLE 14-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq.**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-68 pF 15-68 pF	68-100 pF 15-68 pF 15-68 pF
HS	8.0 MHz 16.0 MHz	10-68 pF 10-22 pF	10-68 pF 10-22 pF
These values are for design guidance only. See notes following Table 14-2.			
Resonators Used:			
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

14.3 Reset

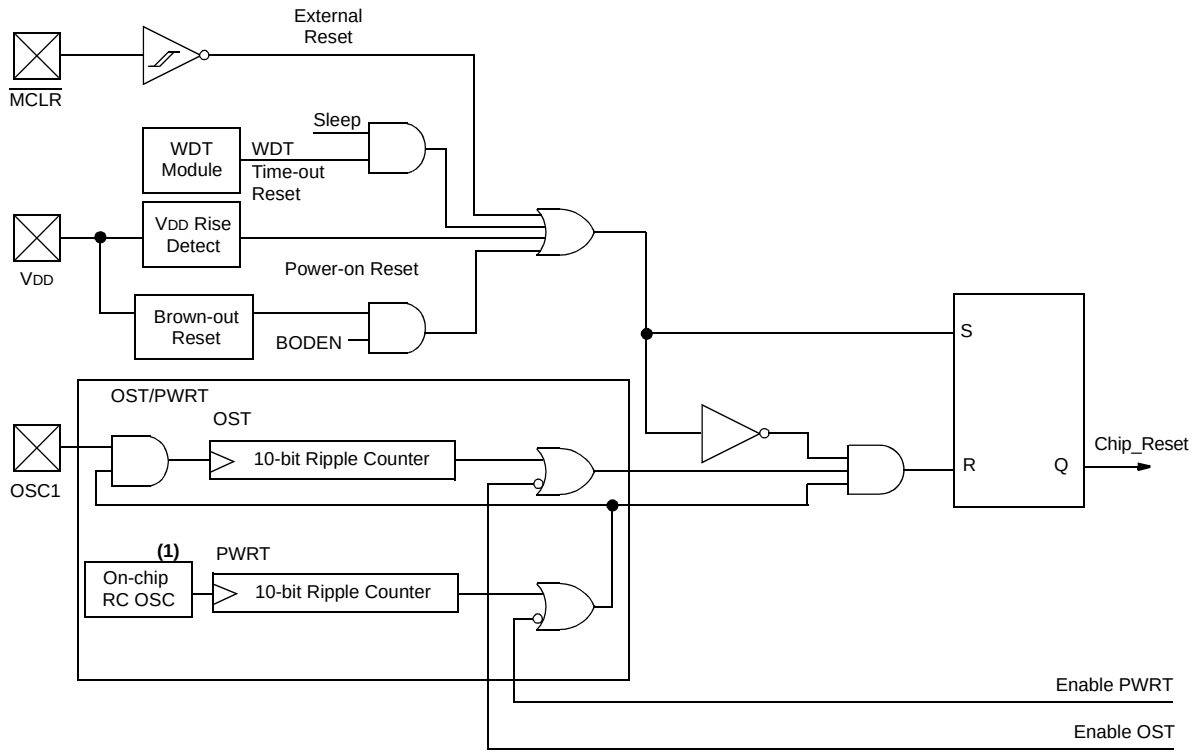
The PIC16F87XA differentiates between various kinds of Reset:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ Reset during normal operation
- $\overline{\text{MCLR}}$ Reset during Sleep
- WDT Reset (during normal operation)
- WDT Wake-up (during Sleep)
- Brown-out Reset (BOR)

Some registers are not affected in any Reset condition. Their status is unknown on POR and unchanged in any other Reset. Most other registers are reset to a "Reset state" on Power-on Reset (POR), on the $\overline{\text{MCLR}}$ and WDT Reset, on $\overline{\text{MCLR}}$ Reset during Sleep and Brown-out Reset (BOR). They are not affected by a WDT wake-up which is viewed as the resumption of normal operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different Reset situations as indicated in Table 14-4. These bits are used in software to determine the nature of the Reset. See Table 14-6 for a full description of Reset states of all registers.

A simplified block diagram of the on-chip Reset circuit is shown in Figure 14-4.

FIGURE 14-4: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKI pin.

17.1 DC Characteristics: PIC16F873A/874A/876A/877A (Industrial, Extended) PIC16LF873A/874A/876A/877A (Industrial)

PIC16LF873A/874A/876A/877A (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC16F873A/874A/876A/877A (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic/ Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		16LF87XA	2.0	—	5.5	V	All configurations (DC to 10 MHz)
D001		16F87XA	4.0	—	5.5	V	All configurations
D001A			VBOR		5.5	V	BOR enabled, FMAX = 14 MHz **(7)**
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See **Section 14.5 "Power-on Reset (POR)"** for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 14.5 "Power-on Reset (POR)"** for details
D005	VBOR	**Brown-out Reset Voltage**	3.65	4.0	4.35	V	BODEN bit in configuration word enabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading, switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: When BOR is enabled, the device will operate correctly until the VBOR voltage trip point is reached.

FIGURE 17-13: SPI SLAVE MODE TIMING (CKE = 0)

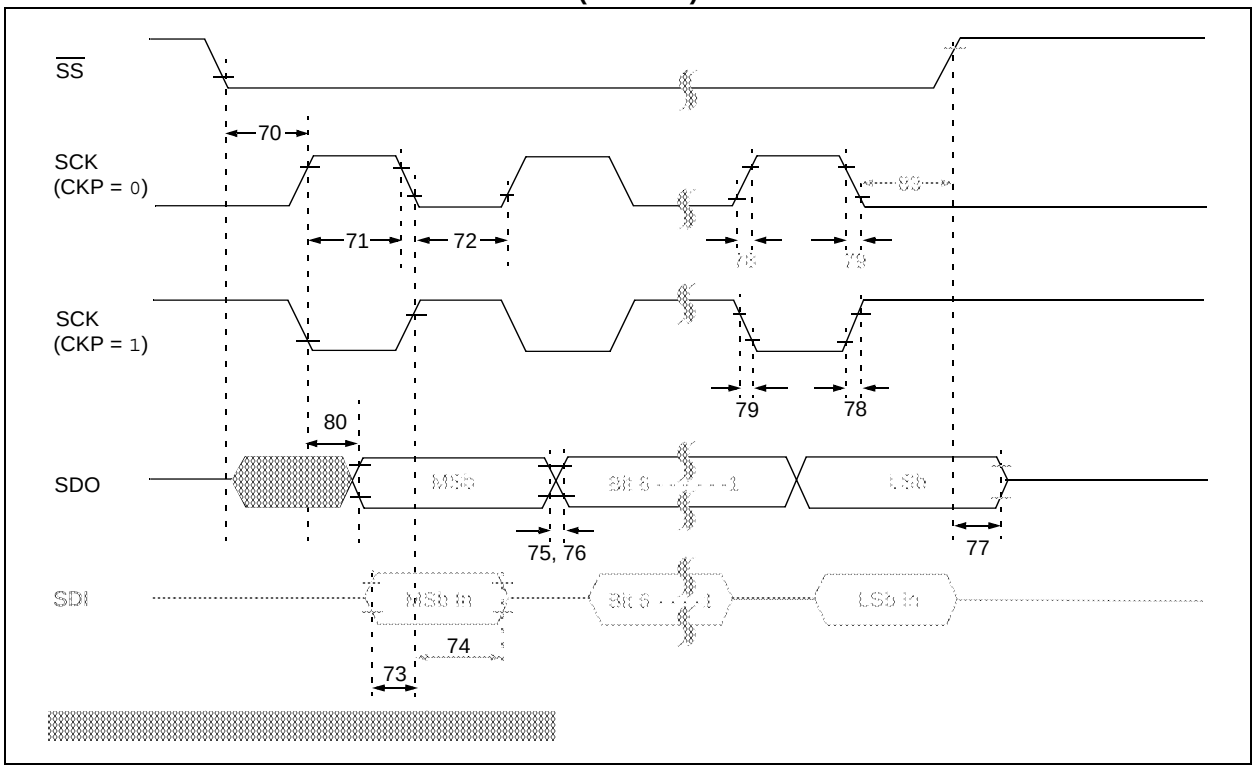


FIGURE 17-14: SPI SLAVE MODE TIMING (CKE = 1)

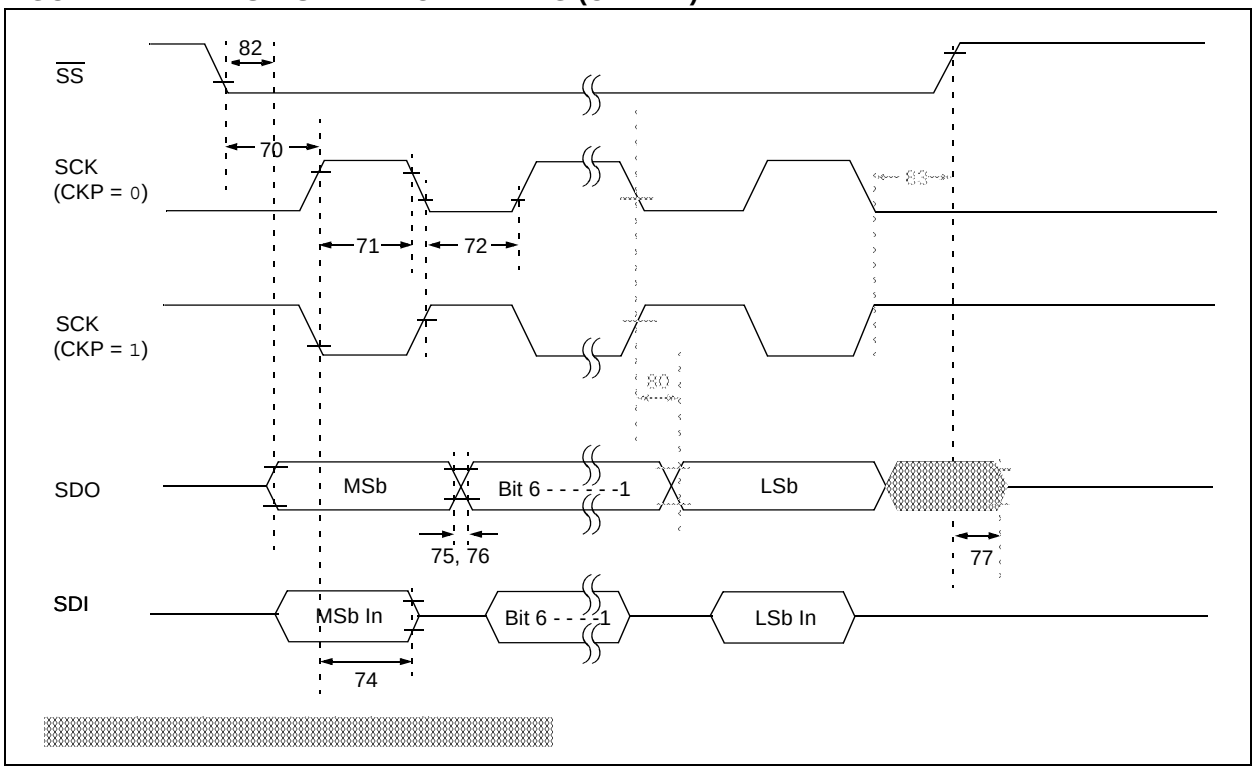


TABLE 17-11: I^2C BUS DATA REQUIREMENTS

Param No.	Sym	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	
			400 kHz mode	0.6	—	µs	
			SSP Module	0.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			SSP Module	0.5 TCY	—		
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	Cb is specified to be from 10 to 400 pF
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A fast mode (400 kHz) I^2C bus device can be used in a standard mode (100 kHz) I^2C bus system, but the requirement that, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, TR MAX. + TSU:DAT = 1000 + 250 = 1250 ns (according to the standard mode I^2C bus specification), before the SCL line is released.

FIGURE 18-7: AVERAGE FOSC vs. VDD FOR VARIOUS VALUES OF R (RC MODE, C = 20 pF, +25°C)

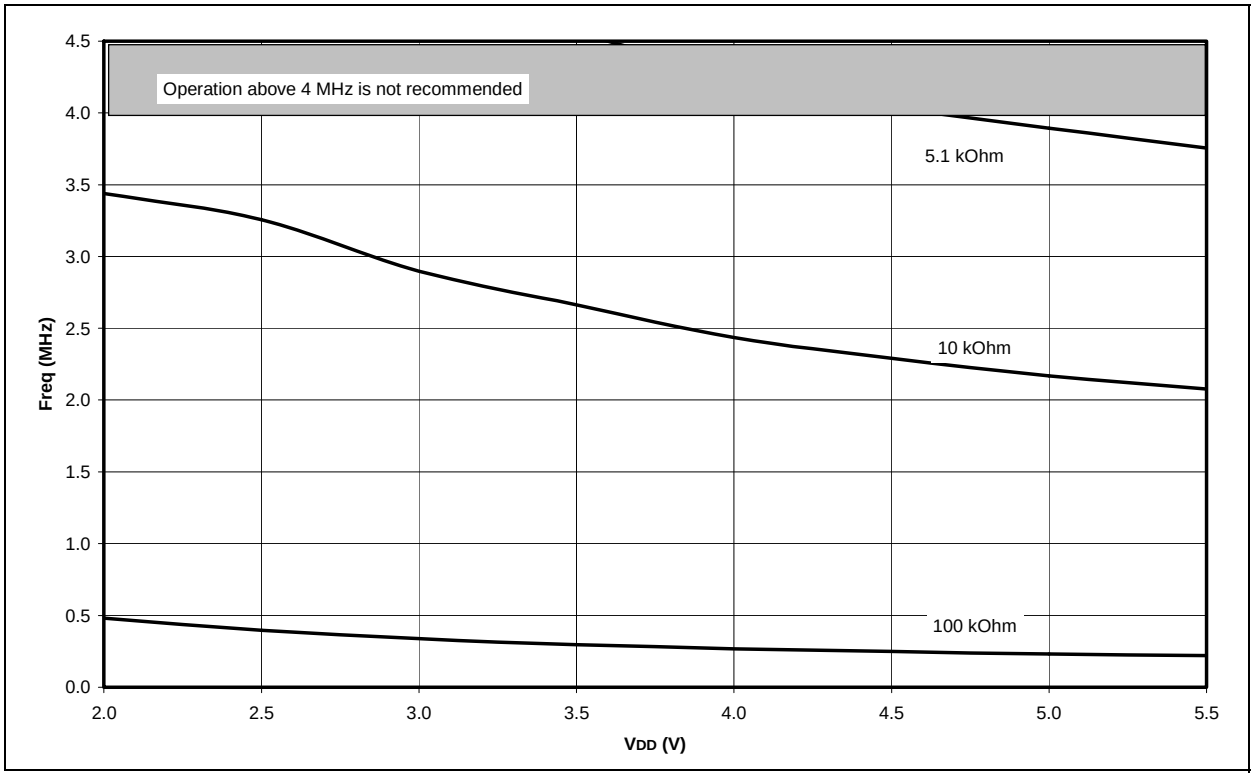


FIGURE 18-8: AVERAGE FOSC vs. VDD FOR VARIOUS VALUES OF R (RC MODE, C = 100 pF, +25°C)

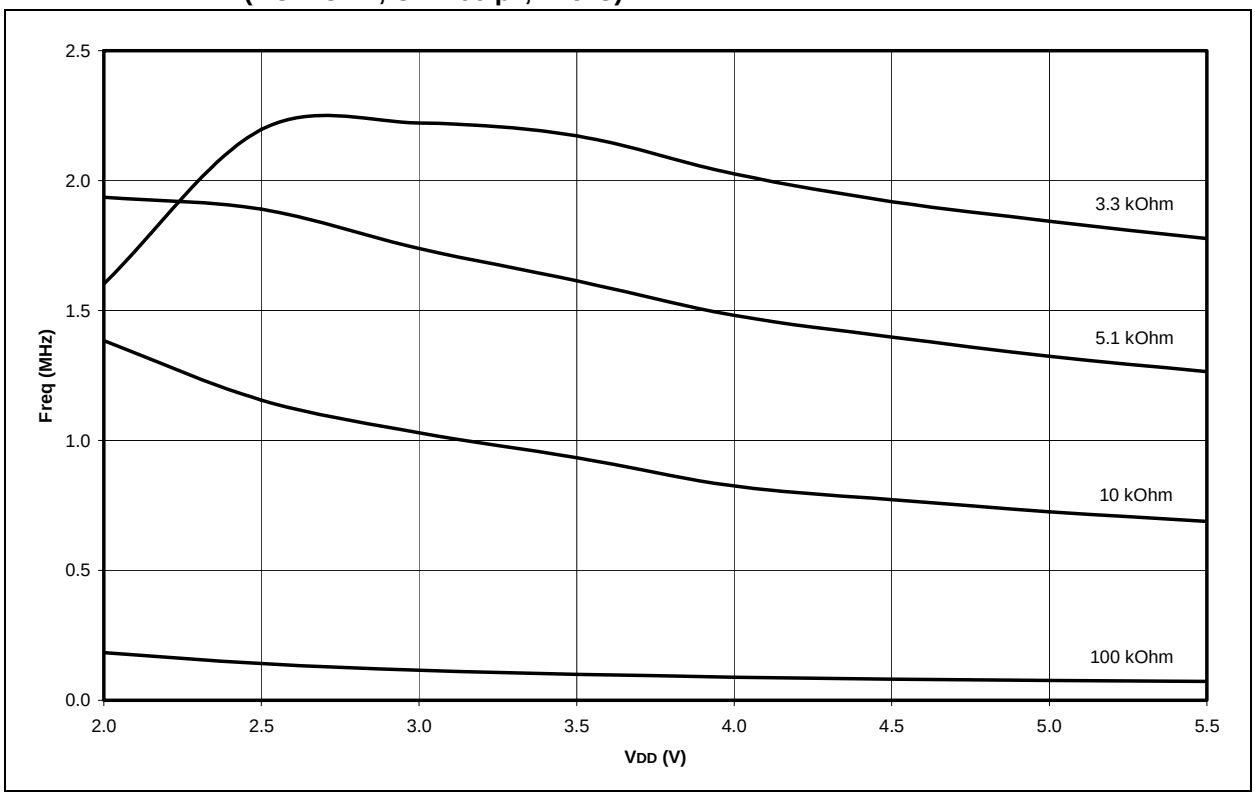


FIGURE 18-21: MINIMUM AND MAXIMUM VIN vs. VDD (ST INPUT, -40°C TO +125°C)

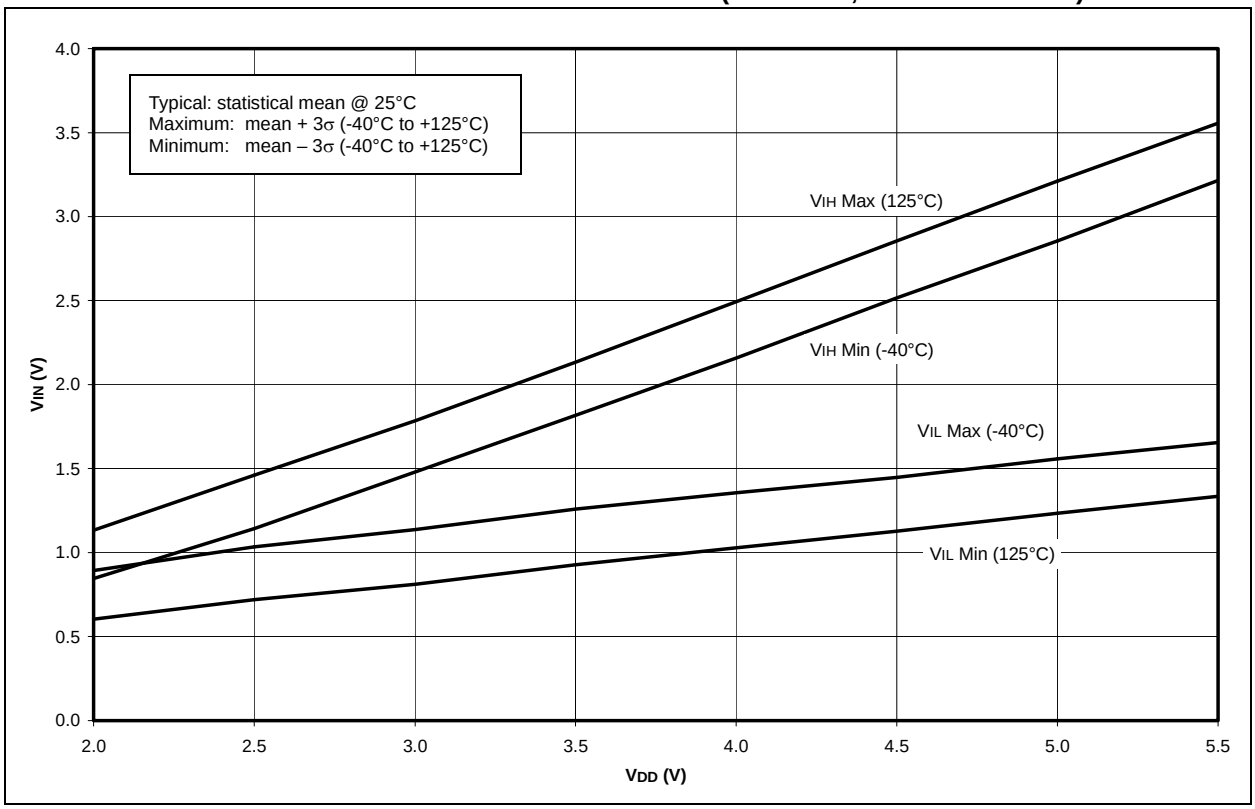
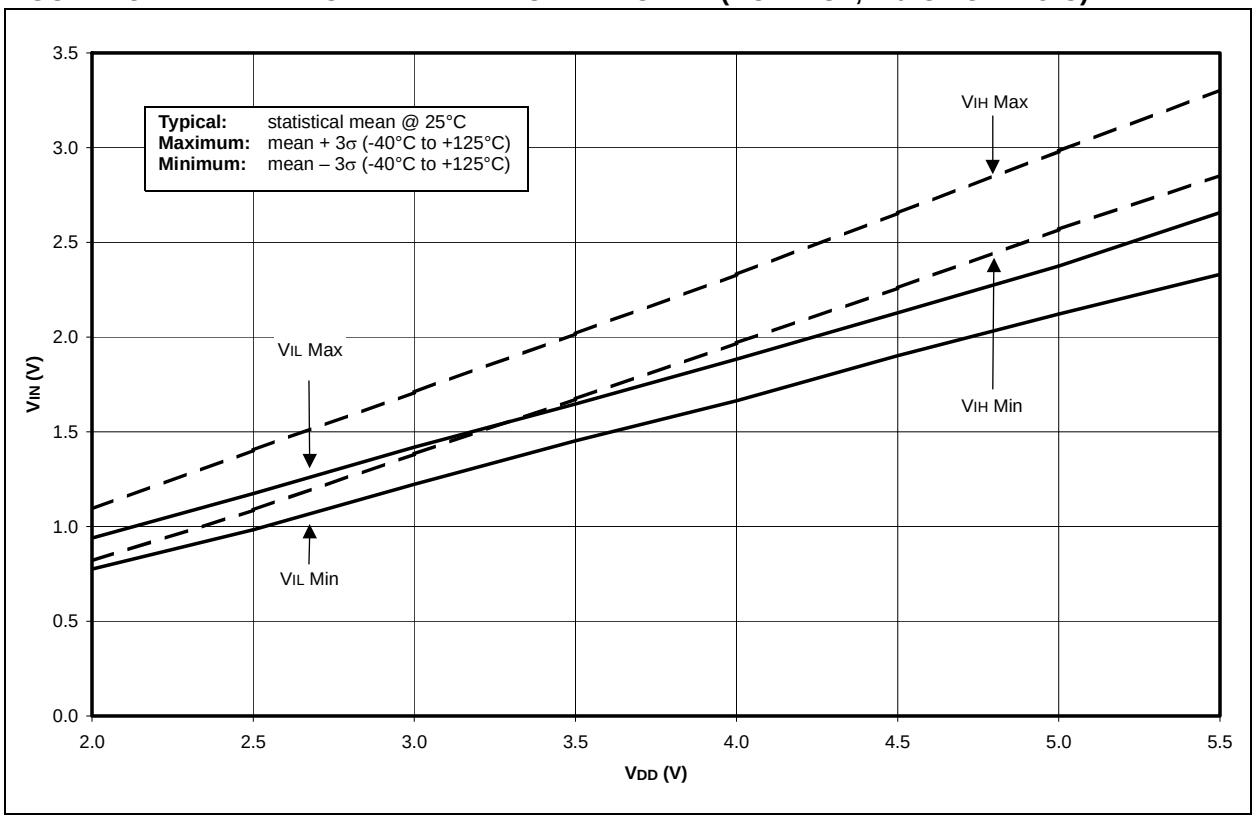
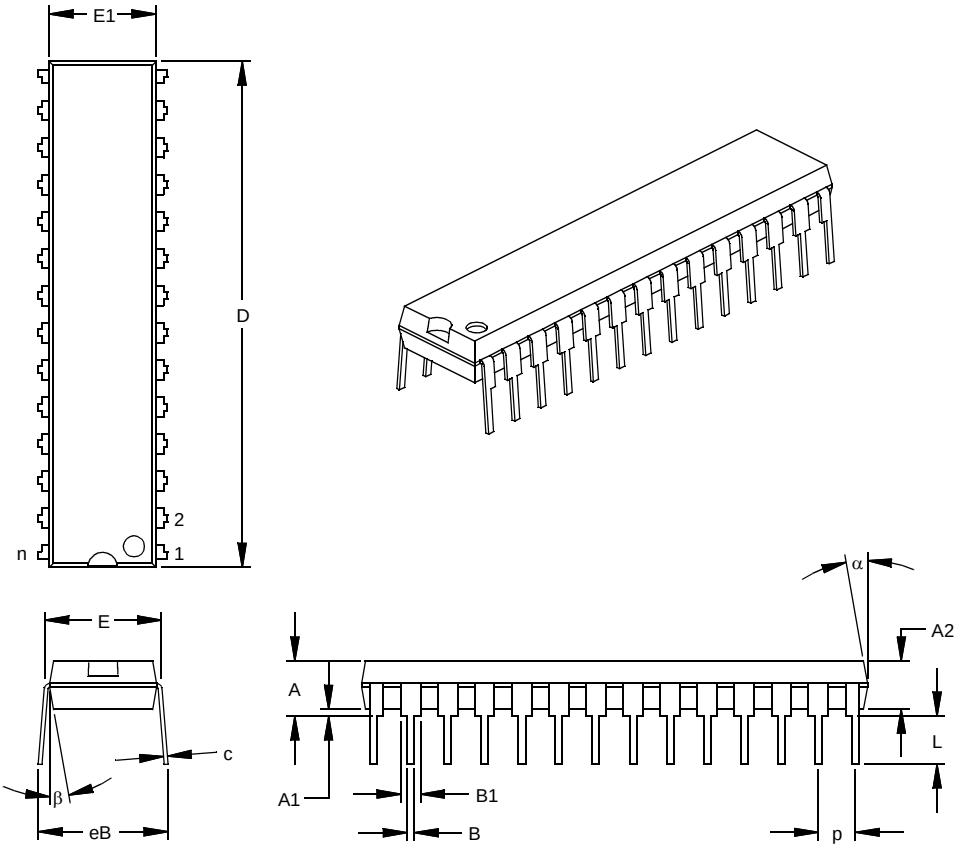


FIGURE 18-22: MINIMUM AND MAXIMUM VIN vs. VDD (I^2C INPUT, -40°C TO +125°C)



28-Lead Skinny Plastic Dual In-line (SP) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.150	.160	3.56	3.81	4.06
Molded Package Thickness	A2	.125	.130	.135	3.18	3.30	3.43
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.310	.325	7.62	7.87	8.26
Molded Package Width	E1	.275	.285	.295	6.99	7.24	7.49
Overall Length	D	1.345	1.365	1.385	34.16	34.67	35.18
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.040	.053	.065	1.02	1.33	1.65
Lower Lead Width	B	.016	.019	.022	0.41	0.48	0.56
Overall Row Spacing §	eB	.320	.350	.430	8.13	8.89	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimension D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-095
Drawing No. C04-070

I

L

M

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- Microchip products meet the specification contained in their particular Microchip Data Sheet.
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